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Funktionssäkerhet hos elektronikkomponenter – Referensbetingelser för felbenägenhet och stressmodeller för omräkning

Electronic components –

Reliability –

Reference conditions for failure rates and stress models for conversion

Som svensk standard gäller europastandarden EN 61709:2017. Den svenska standarden innehåller den officiella engelska språkversionen av EN 61709:2017.

Nationellt förord

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English Version

Electric components - Reliability - Reference conditions for
failure rates and stress models for conversion
(IEC 61709:2017)

Composants électriques - Fiabilité - Conditions de référence
pour les taux de défaillance et modèles de contraintes pour
la conversion
(IEC 61709:2017)

Bauelemente der Elektronik - Zuverlässigkeit -
Referenzbedingungen für Ausfallraten und
Beanspruchungsmodelle zur Umrechnung
(IEC 61709:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 56/1714/FDIS, future edition 3 of IEC 61709, prepared by IEC/TC 56 "Dependability" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61709:2017.

The following dates are fixed:

- latest date by which the document has to be (dop) 2017-12-24
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2020-03-24
standards conflicting with the
document have to be withdrawn

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Endorsement notice

The text of the International Standard IEC 61709:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60300-3-2:2004	NOTE	Harmonized as EN 60300-3-2:2005.
IEC 60300-3-3	NOTE	Harmonized as EN 60300-3-3.
IEC 60721 (series)	NOTE	Harmonized as EN 60721 (series).
IEC 60721-3-3	NOTE	Harmonized as EN 60721-3-3.
IEC 60721-3-4	NOTE	Harmonized as EN 60721-3-4.
IEC 60721-3-5	NOTE	Harmonized as EN 60721-3-5.
IEC 60721-3-7	NOTE	Harmonized as EN 60721-3-7.
IEC 61014:2003	NOTE	Harmonized as EN 61014:2003.
IEC 61360 (series)	NOTE	Harmonized as EN 61360 (series).
IEC 61360-1:2009	NOTE	Harmonized as EN 61360-1:2010.
IEC 61360-4:2005	NOTE	Harmonized as EN 61360-4:2005.
IEC 61508 (series)	NOTE	Harmonized as EN 61508 (series).
IEC 61649:2008	NOTE	Harmonized as EN 61649:2008.
IEC 61703:2002	NOTE	Harmonized as EN 61703:2002.
IEC 61710	NOTE	Harmonized as EN 61710.

IEC 61810-2:2011	NOTE	Harmonized as EN 61810-2:2011.
IEC 61810-2-1:2011	NOTE	Harmonized as EN 61810-2-1:2011.
IEC 62007 (series)	NOTE	Harmonized as EN 62007 (series).
IEC 62741	NOTE	Harmonized as EN 62741.
IEC 62308:2006	NOTE	Harmonized as EN 62308:2006.

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-192	2015	International electrotechnical vocabulary - Part 192: Dependability	-	-

CONTENTS

FOREWORD.....	9
INTRODUCTION.....	11
1 Scope.....	12
2 Normative references	12
3 Terms, definitions and symbols	12
3.1 Terms and definitions.....	12
3.2 Symbols.....	16
4 Context and conditions	17
4.1 Failure modes and mechanisms.....	17
4.2 Thermal modelling	18
4.3 Mission profile consideration.....	18
4.3.1 General	18
4.3.2 Operating and non-operating conditions	18
4.3.3 Dormancy	19
4.3.4 Storage	19
4.4 Environmental conditions	19
4.5 Components choice	21
4.6 Reliability growth during the deployment phase of new equipment	22
4.7 How to use this document.....	23
5 Generic reference conditions and stress models.....	24
5.1 Recommended generic reference conditions.....	24
5.2 Generic stress models	25
5.2.1 General	25
5.2.2 Stress factor for voltage dependence, π_U	26
5.2.3 Stress factor for current dependence, π_I	26
5.2.4 Stress factor for temperature dependence, π_T	26
5.2.5 Environmental application factor, π_E	28
5.2.6 Dependence on switching rate, π_S	28
5.2.7 Dependence on electrical stress, π_{ES}	29
5.2.8 Other factors of influence	29
6 Integrated semiconductor circuits	29
6.1 Specific reference conditions	29
6.2 Specific stress models	31
6.2.1 General	31
6.2.2 Voltage dependence, factor π_U	32
6.2.3 Temperature dependence, factor π_T	32
7 Discrete semiconductors	35
7.1 Specific reference conditions	35
7.2 Specific stress models	36
7.2.1 General	36
7.2.2 Voltage dependence for transistors, factor π_U	37
7.2.3 Temperature dependence, factor π_T	37
8 Optoelectronic components	39

8.1	Specific reference conditions	39
8.2	Specific stress models	41
8.2.1	General	41
8.2.2	Voltage dependence, factor π_U	41
8.2.3	Current dependence, factor π_I	41
8.2.4	Temperature dependence, factor π_T	42
9	Capacitors	44
9.1	Specific reference conditions	44
9.2	Specific stress model	44
9.2.1	General	44
9.2.2	Voltage dependence, factor π_U	44
9.2.3	Temperature dependence, factor π_T	46
10	Resistors and resistor networks	47
10.1	Specific reference conditions	47
10.2	Specific stress models	48
10.2.1	General	48
10.2.2	Temperature dependence, factor π_T	48
11	Inductors, transformers and coils	49
11.1	Reference conditions	49
11.2	Specific stress model	49
11.2.1	General	49
11.2.2	Temperature dependence, factor π_T	49
12	Microwave devices	50
12.1	Specific reference conditions	50
12.2	Specific stress models	51
13	Other passive components	51
13.1	Specific reference conditions	51
13.2	Specific stress models	51
14	Electrical connections	51
14.1	Specific reference conditions	51
14.2	Specific stress models	52
15	Connectors and sockets	52
15.1	Reference conditions	52
15.2	Specific stress models	52
16	Relays	52
16.1	Reference conditions	52
16.2	Specific stress models	53
16.2.1	General	53
16.2.2	Dependence on switching rate, factor π_S	53
16.2.3	Dependence on electrical stress, factor π_{ES}	54
16.2.4	Temperature dependence, factor π_T	55
17	Switches and push-buttons	55
17.1	Specific reference conditions	55
17.2	Specific stress model	56
17.2.1	General	56

17.2.2	Dependence on electrical stress, factor π_{ES}	56
18	Signal and pilot lamps	57
18.1	Specific reference conditions	57
18.2	Specific stress model	57
18.2.1	General	57
18.2.2	Voltage dependence, factor π_U	58
19	Printed circuit boards (PCB)	58
20	Hybrid circuits	58
Annex A (normative)	Failure modes of components	59
Annex B (informative)	Thermal model for semiconductors	62
B.1	Thermal model	62
B.2	Junction temperature calculation	63
B.3	Thermal resistance evaluation	64
B.4	Power dissipation of an integrated circuit P	65
Annex C (informative)	Failure rate prediction	68
C.1	General	68
C.2	Failure rate prediction for assemblies	68
C.2.1	General	68
C.2.2	Assumptions and limitations	69
C.2.3	Process for failure rate prediction	69
C.2.4	Prediction models	70
C.2.5	Other methods of reliability prediction	71
C.2.6	Validity considerations of reliability models and predictions	72
C.3	Component considerations	73
C.3.1	Component model	73
C.3.2	Components classification	73
C.4	General consideration about failure rate	73
C.4.1	General	73
C.4.2	General behaviour of the failure rate of components	74
C.4.3	Expected values of failure rate	75
C.4.4	Sources of variation in failure rates	75
Annex D (informative)	Considerations on mission profile	77
D.1	General	77
D.2	Dormancy	77
D.3	Mission profile	78
D.4	Example of mission profile	79
Annex E (informative)	Useful life models	80
E.1	General	80
E.2	Power transistors	80
E.3	Optocouplers	80
E.3.1	Useful life L	80
E.3.2	Factor L_0	81
E.3.3	Factor κ_0	81
E.3.4	Factor κ_1	82
E.3.5	Factor κ_2	82
E.3.6	Factor κ_3	82
E.4	LED and LED modules	83

E.4.1	Useful life L	83
E.4.2	Factor L_0	83
E.4.3	Factor κ_0	84
E.4.4	Factor κ_1	84
E.4.5	Factor κ_2	85
E.4.6	Factor κ_3	85
E.5	Aluminium, non-solid electrolyte capacitors	85
E.6	Relays	86
E.7	Switches and keyboards	86
E.8	Connectors	86
Annex F (informative)	Physics of failure	87
F.1	General	87
F.2	Failure mechanisms of integrated circuits	88
Annex G (informative)	Considerations for the design of a data base on failure rates	89
G.1	General	89
G.2	Data collection acquisition – collection process	89
G.3	Which data to collect and how to collect it	89
G.4	Calculation and decision making	90
G.5	Data descriptions	90
G.6	Identification of components	90
G.6.1	General	90
G.6.2	Component identification	91
G.6.3	Component technology	91
G.7	Specification of components	91
G.7.1	General	91
G.7.2	Electrical specification of components	91
G.7.3	Environmental specification of components	92
G.8	Field related issues data	92
G.8.1	General	92
G.8.2	Actual field conditions	92
G.8.3	Data on field failures	92
G.9	Test related issues data	93
G.9.1	General	93
G.9.2	Actual test conditions	93
G.9.3	Data on test failures	93
G.10	Failure rate database attributes	94
Annex H (informative)	Potential sources of failure rate data and methods of selection	96
H.1	General	96
H.2	Data source selection	96
H.3	User data	97
H.4	Manufacturer's data	97
H.5	Handbook reliability data	98
H.5.1	General	98
H.5.2	Using handbook data with this document	98
H.5.3	List of available handbooks	99
Annex I (informative)	Overview of component classification	102
I.1	General	102
I.2	The IEC 61360 system	102

I.3	Other systems.....	110
I.3.1	General	110
I.3.2	NATO stock numbers.....	110
I.3.3	UNSPSC codes	110
I.3.4	STEP/EXPRESS.....	110
I.3.5	IECQ	110
I.3.6	ECALS	111
I.3.7	ISO 13584	111
I.3.8	MIL specifications.....	111
Annex J (informative)	Presentation of component reliability data.....	112
J.1	General.....	112
J.2	Identification of components	112
J.2.1	General	112
J.2.2	Component identification	113
J.2.3	Component technology	113
J.3	Specification of components	113
J.3.1	General	113
J.3.2	Electrical specification of components	113
J.3.3	Environmental specification of components	113
J.4	Test related issues data.....	113
J.4.1	General	113
J.4.2	Actual test conditions	114
J.5	Data on test failures.....	114
Annex K (informative)	Examples	116
K.1	Integrated circuit.....	116
K.2	Transistor	116
K.3	Capacitor	116
K.4	Relay.....	117
Bibliography.....		118
Figure 1 – Comparison of the temperature dependence of π_T for CMOS IC.....		24
Figure 2 – Selection of stress regions in accordance with current and voltage-operating conditions		54
Figure 3 – Selection of stress regions in accordance with current and voltage-operating conditions		56
Figure B.1 – Temperatures inside equipment.....		63
Figure B.2 – Thermal resistance model.....		64
Figure D.1 – Mission profile		79
Table 1 – Basic environments		20
Table 2 – Values of environmental parameters for basic environments		21
Table 3 – Recommended reference conditions for environmental and mechanical stresses.....		25
Table 4 – Environmental application factor, π_E		28
Table 5 – Memory.....		30
Table 6 – Microprocessors and peripherals, microcontrollers and signal processors		30
Table 7 – Digital logic families and bus interfaces, bus driver and receiver circuits		30

Table 8 – Analog ICs	31
Table 9 – Application-specific ICs (ASICs).....	31
Table 10 – Constants for voltage dependence	32
Table 11 – Factor π_U for digital CMOS-family ICs.....	32
Table 12 – Factor π_U for bipolar analog ICs	32
Table 13 – Constants for temperature dependence	32
Table 14 – Factor π_T for ICs (without EPROM; FLASH-EPROM; OTPROM; EEPROM; EAROM)	34
Table 15 – Factor π_T for EPROM; FLASH-EPROM; OTPROM; EEPROM; EAROM.....	34
Table 16 – Transistors common, low frequency.....	35
Table 17 – Transistors, microwave, (e.g. RF > 800 MHz)	35
Table 18 – Diodes.....	36
Table 19 – Power semiconductors	36
Table 20 – Constants for voltage dependence of transistors	37
Table 21 – Factor π_U for transistors	37
Table 22 – Constants for temperature dependence of discrete semiconductors	37
Table 23 – Factor π_T for transistors, reference and microwave diodes	38
Table 24 – Factor π_T for diodes (without reference and microwave diodes) and power semiconductors.....	38
Table 25 – Optoelectronic semiconductor signal receivers	39
Table 26 – LEDs, IREDs, laser diodes and transmitter components	39
Table 27 – Optocouplers and light barriers.....	40
Table 28 – Passive optical components	40
Table 29 – Transceiver, transponder and optical sub-equipment.....	40
Table 30 – Constants for voltage dependence of phototransistors.....	41
Table 31 – Factor π_U for phototransistors	41
Table 32 – Constants for current dependence of LEDs and IREDs.....	42
Table 33 – Factor π_I for LEDs and IREDs.....	42
Table 34 – Constants for temperature dependence of optoelectronic components	42
Table 35 – Factor π_T for optical components.....	43
Table 36 – Capacitors	44
Table 37 – Constants for voltage dependence of capacitors.....	45
Table 38 – Factor π_U for capacitors	45
Table 39 – Constants for temperature dependence of capacitors	46
Table 40 – Factor π_T for capacitors.....	47
Table 41 – Resistors and resistor networks.....	48
Table 42 – Constants for temperature dependence of resistors.....	48
Table 43 – Factor π_T for resistors	49
Table 44 – Inductors, transformers and coils.....	49
Table 45 – Constants for temperature dependence of inductors, transformers and coils	49
Table 46 – Factor π_T for inductors, transformers and coils	50

Table 47 – Microwave devices	50
Table 48 – Other passive components	51
Table 49 – Electrical connections.....	52
Table 50 – Connectors and sockets	52
Table 51 – Relays.....	53
Table 52 – Factor π_{ES} for low current relays	54
Table 53 – Factor π_{ES} for general purpose relays	54
Table 54 – Factor π_{ES} for automotive relays.....	55
Table 55 – Constants for temperature dependence of relays.....	55
Table 56 – Factor π_T for relays	55
Table 57 – Switches and push-buttons.....	56
Table 58 – Factor π_{ES} for switches and push-buttons for low electrical stress.....	57
Table 59 – Factor π_{ES} for switches and push-buttons for higher electrical stress	57
Table 60 – Signal and pilot lamps	57
Table 61 – Factor π_U for signal and pilot lamps.....	58
Table A.1 – Failure modes: ICs (digital)	59
Table A.2 – Failure modes: transistors, diodes, optocouplers.....	60
Table A.3 – Failure modes: LEDs.....	60
Table A.4 – Failure modes: laser diodes and modules	60
Table A.5 – Failure modes: photodiodes and receiver modules	60
Table A.6 – Failure modes: capacitors	61
Table A.7 – Failure modes: resistors, inductive devices, relays.....	61
Table B.1 – Thermal resistance as a function of package type, pin number and airflow factor	65
Table B.2 – Typical values of ν are K	65
Table B.3 – Values of P_{DC} and P_f	66
Table E.1 – Useful life limitations for switches and keyboards.....	86
Table F.1 – Failure mechanism for Integrated circuits	88
Table G.1 – Reliability prediction database attributes.....	95
Table H.1 – Result of calculation for transistors common, low frequency.....	99
Table H.2 – Sources of reliability data (in alphabetical order).....	99
Table I.1 – Classification tree (IEC 61360-4).....	103

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRIC COMPONENTS –
RELIABILITY –
REFERENCE CONDITIONS FOR FAILURE RATES
AND STRESS MODELS FOR CONVERSION****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 61709 has been prepared by IEC technical committee 56: Dependability.

This third edition cancels and replaces the second edition, published in 2011. This edition constitutes a technical revision. This third edition is a merger of IEC 61709:2011 and IEC TR 62380:2004.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of 4.5 Components choice, 4.6 Reliability growth during the deployment phase of new equipment, 4.7 How to use this document, and of Clause 19 Printed circuit boards (PCB) and Clause 20 Hybrid circuits with respect to IEC TR 62380;
- b) addition of failure modes of components in Annex A;

- c) modification of Annex B, Thermal model for semiconductors, adopted and revised from IEC TR 62380;
- d) modification of Annex D, Considerations on mission profile;
- e) modification of Annex E, Useful life models, adopted and revised from IEC TR 62380;
- f) revision of Annex F (former B.2.6.4), Physics of failure;
- g) addition of Annex G (former Annex C), Considerations for the design of a data base on failure rates, complemented with parts of IEC 60319;
- h) addition of Annex H, Potential sources of failure rate data and methods of selection;
- i) addition of Annex J, Presentation of component reliability data, based on IEC 60319.

The text of this standard is based on the following documents:

FDIS	Report on voting
56/1714/FDIS	56/1721/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

This document is intended for the reliability prediction of electric components as used in equipment and is aimed at organizations that have their own data and describes how to state and use that data in order to perform reliability predictions.

It can also be used to allow an organization to set up a failure rate database and describes the reference conditions for which field failure rates should be stated. The reference conditions adopted in this document are typical of the majority of applications of components in equipment however when components operate under other conditions the users may consider stating these conditions as their reference conditions.

Using the presented stress models allows extrapolation of failure rates from reference conditions to other operating conditions which in turn permits the prediction of failure rates at assembly level. This allows estimation of the effect of design changes or changes in the environmental conditions on component reliability. Reliability prediction is most useful in the early design phase of equipment. It can be used, for example, to identify potential reliability problems, the planning of logistic support strategies and the evaluation of designs.

The stress models contained herein are generic and are as simple as possible while still being comparable with more complex equations contained in other models. The predictions generated using this document have a wide range of prediction accuracy.

This document does not contain failure rates, but it describes how they can be stated and used. This approach allows a user to select the most relevant and up to date failure rates for the prediction from a source that they select. This document also contains information on how to select the data that can be used in the presented models.

The failure rates considered in this document are assumed to be constant, either for an unlimited period of operation (general case) or for limited periods. The limitation of life is called useful life and applies only for some few component families, reaching the wear-out failure period (during which the failure rate is increasing) within the normal period of use. It is hence assumed that during useful life, the failure rate can be considered constant for any practical use.

For the purposes of this document the term electric component includes the commonly used terms “electronic component”, “electrical component” and “electro-mechanical component”.

ELECTRIC COMPONENTS – RELIABILITY – REFERENCE CONDITIONS FOR FAILURE RATES AND STRESS MODELS FOR CONVERSION

1 Scope

This document gives guidance on the use of failure rate data for reliability prediction of electric components used in equipment.

The method presented in this document uses the concept of reference conditions which are the typical values of stresses that are observed by components in the majority of applications.

Reference conditions are useful since they provide a known standard basis from which failure rates can be modified to account for differences in environment from the environments taken as reference conditions. Each user can use the reference conditions defined in this document or use their own. When failure rates stated at reference conditions are used it allows realistic reliability predictions to be made in the early design phase.

The stress models described herein are generic and can be used as a basis for conversion of failure rate data given at these reference conditions to actual operating conditions when needed and this simplifies the prediction approach. Conversion of failure rate data is only possible within the specified functional limits of the components.

This document also gives guidance on how a database of component failure data can be constructed to provide failure rates that can be used with the included stress models. Reference conditions for failure rate data are specified, so that data from different sources can be compared on a uniform basis. If failure rate data are given in accordance with this document then additional information on the specified conditions can be dispensed with.

This document does not provide base failure rates for components – rather it provides models that allow failure rates obtained by other means to be converted from one operating condition to another operating condition.

The prediction methodology described in this document assumes that the parts are being used within its useful life. The methods in this document have a general application but are specifically applied to a selection of component types as defined in Clauses 6 to 20 and I.2.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-192:2015, *International electrotechnical vocabulary – Part 192: Dependability*